

E Series Power MOSFET

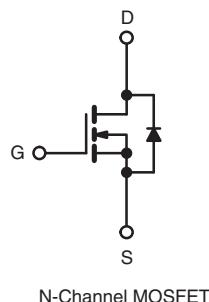
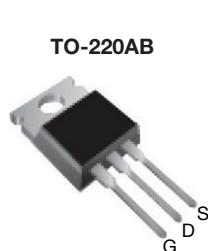
PRODUCT SUMMARY	
V_{DS} (V) at T_J max.	550
$R_{DS(on)}$ max. at 25 °C (Ω)	$V_{GS} = 10$ V 0.184
Q_g max. (nC)	92
Q_{gs} (nC)	10
Q_{gd} (nC)	19
Configuration	Single

FEATURES

- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Low gate charge (Q_g)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE



APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- Consumer electronics
- Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free and Halogen-free	SiHP20N50E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	
Continuous Drain Current ($T_J = 150$ °C)	V_{GS} at 10 V	19	A
		12	
Pulsed Drain Current ^a	I_{DM}	42	
Linear Derating Factor		1.4	W/°C
Single Pulse Avalanche Energy ^b	E_{AS}	204	mJ
Maximum Power Dissipation	P_D	179	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	°C
Drain-Source Voltage Slope	$V_{DS} = 0$ V to 80 % V_{DS}	dV/dt	V/ns
Reverse Diode dV/dt ^d		70	
Reverse Diode dV/dt ^d		32	
Soldering Recommendations (Peak Temperature) ^c	for 10 s	300	°C

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω, $I_{AS} = 3.8$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/μs, starting $T_J = 25$ °C.

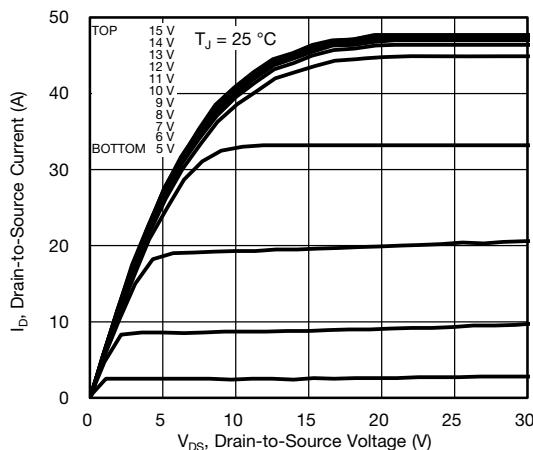
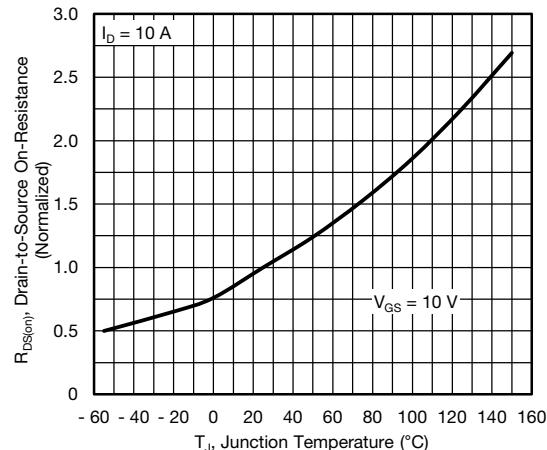
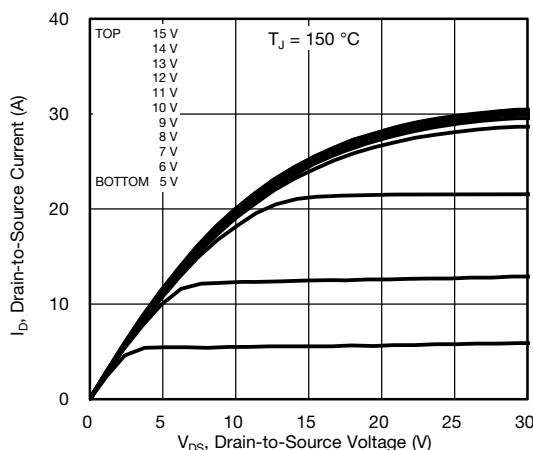
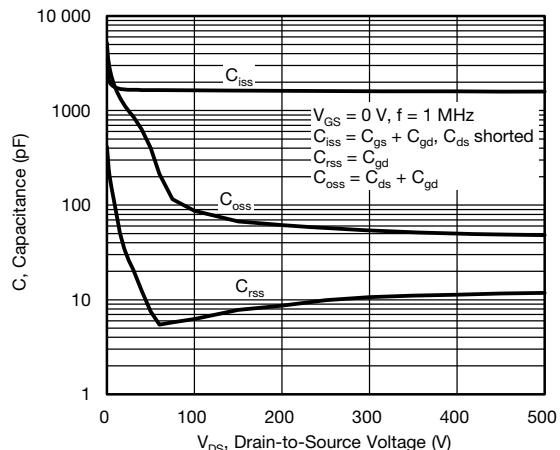
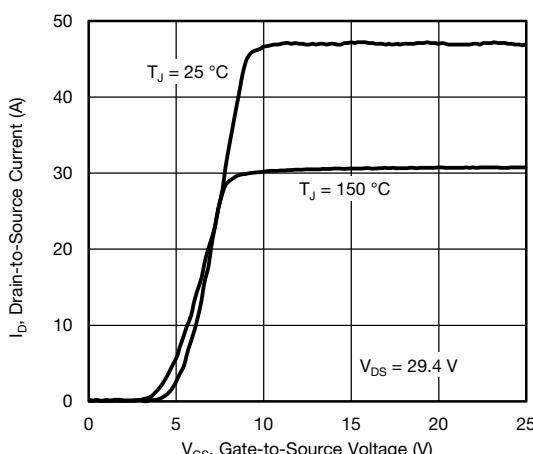
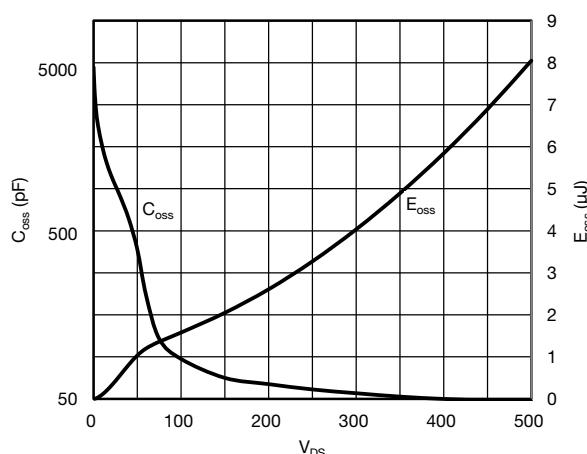
THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.7	

SPECIFICATIONS ($T_J = 25^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$		500	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25°C , $I_D = 1 \text{ mA}$		-	0.59	-	$\text{V}/^\circ\text{C}$
Gate-Source Threshold Voltage (N)	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$		2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500 \text{ V}$, $V_{GS} = 0 \text{ V}$		-	-	1	μA
		$V_{DS} = 400 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^\circ\text{C}$		-	-	10	
Drain-Source On-State Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$	$I_D = 10 \text{ A}$	-	0.160	0.184	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 30 \text{ V}$, $I_D = 10 \text{ A}$		-	4.4	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 100 \text{ V}$, $f = 1 \text{ MHz}$		-	1640	-	pF
Output Capacitance	C_{oss}			-	87	-	
Reverse Transfer Capacitance	C_{rss}			-	6	-	
Effective Output Capacitance, Energy Related ^a	$C_{o(er)}$	$V_{DS} = 0 \text{ V to } 400 \text{ V}$, $V_{GS} = 0 \text{ V}$		-	73	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	222	-	
Total Gate Charge	Q_g			-	46	92	nC
Gate-Source Charge	Q_{gs}	$V_{GS} = 10 \text{ V}$	$I_D = 10 \text{ A}$, $V_{DS} = 400 \text{ V}$	-	10	-	
Gate-Drain Charge	Q_{gd}			-	19	-	
Turn-On Delay Time	$t_{d(on)}$			-	17	34	ns
Rise Time	t_r	$V_{DD} = 400 \text{ V}$, $I_D = 10 \text{ A}$, $V_{GS} = 10 \text{ V}$, $R_g = 9.1 \Omega$		-	27	54	
Turn-Off Delay Time	$t_{d(off)}$			-	48	96	
Fall Time	t_f			-	25	50	
Gate Input Resistance	R_g	$f = 1 \text{ MHz}$, open drain		-	0.83	-	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_s	MOSFET symbol showing the integral reverse p - n junction diode		-	-	19	A
Pulsed Diode Forward Current	I_{SM}			-	-	42	
Diode Forward Voltage	V_{SD}	$T_J = 25^\circ\text{C}$, $I_S = 10 \text{ A}$, $V_{GS} = 0 \text{ V}$		-	-	1.2	V
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}$, $I_F = I_S = 10 \text{ A}$, $dl/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 25 \text{ V}$		-	293	-	ns
Reverse Recovery Charge	Q_{rr}			-	4.0	-	μC
Reverse Recovery Current	I_{RRM}			-	26	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

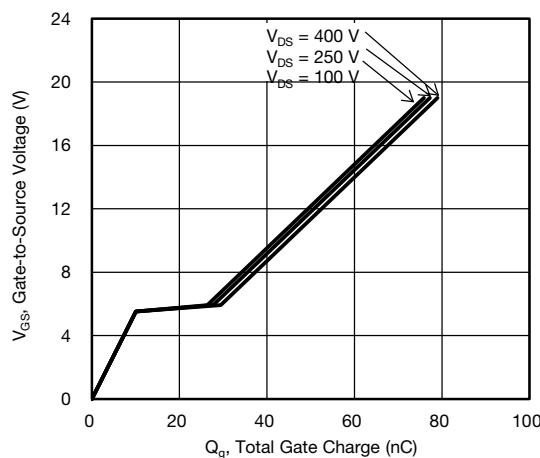


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

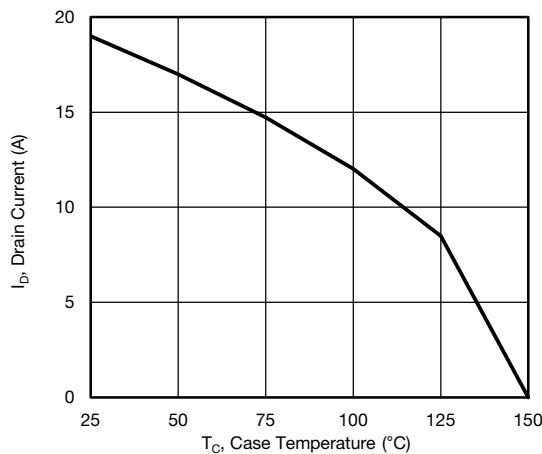


Fig. 10 - Maximum Drain Current vs. Case Temperature

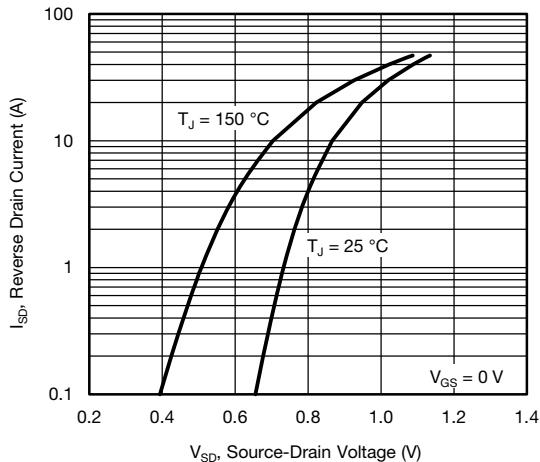


Fig. 8 - Typical Source-Drain Diode Forward Voltage

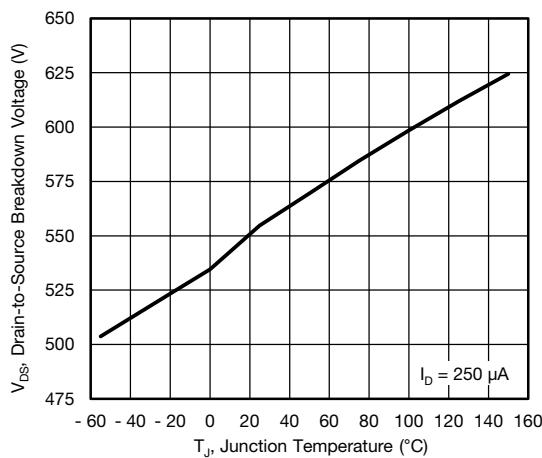


Fig. 11 - Temperature vs. Drain-to-Source Voltage

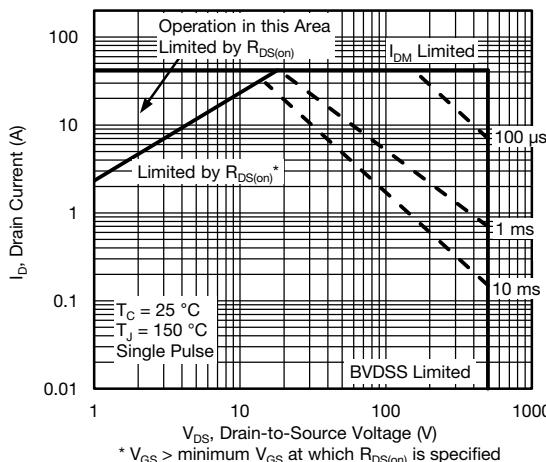


Fig. 9 - Maximum Safe Operating Area

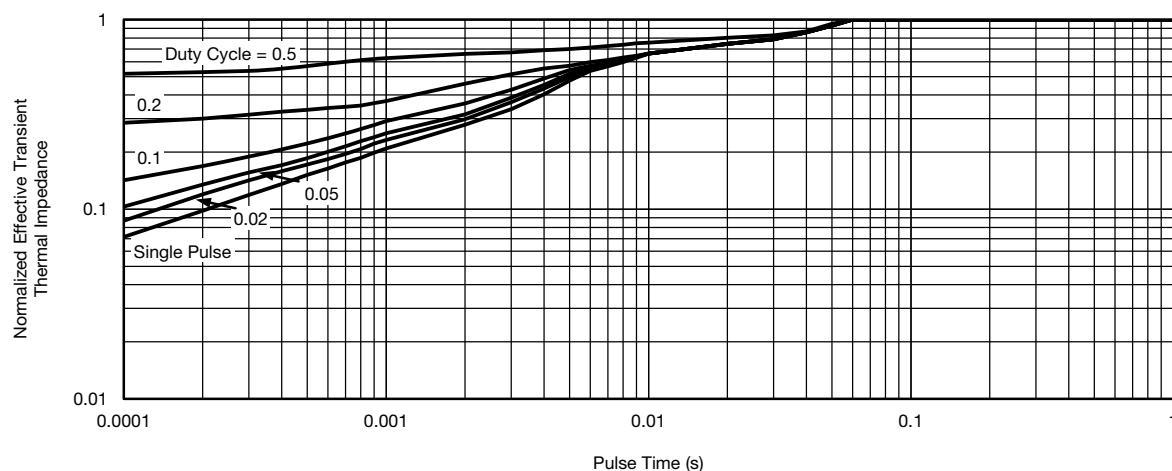


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

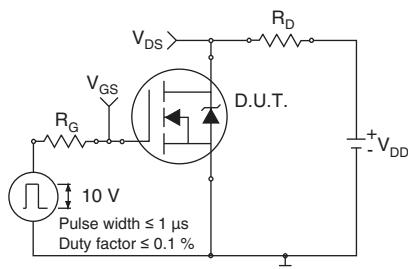


Fig. 13 - Switching Time Test Circuit

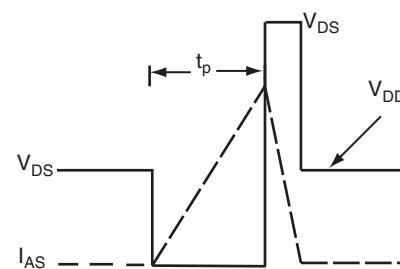


Fig. 16 - Unclamped Inductive Waveforms

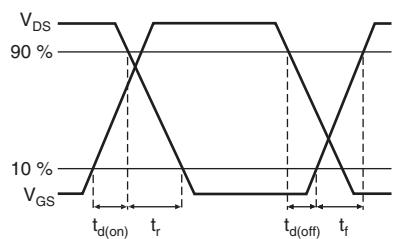


Fig. 14 - Switching Time Waveforms

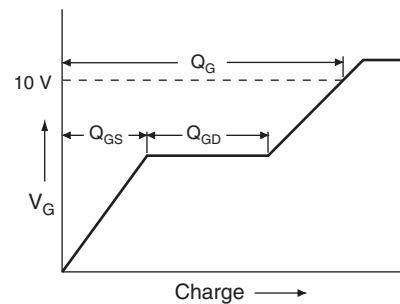


Fig. 17 - Basic Gate Charge Waveform

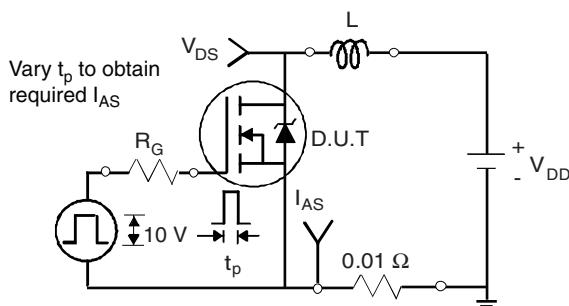


Fig. 15 - Unclamped Inductive Test Circuit

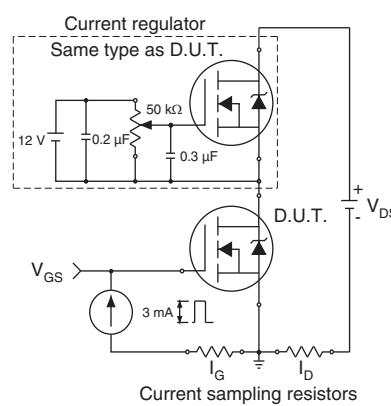
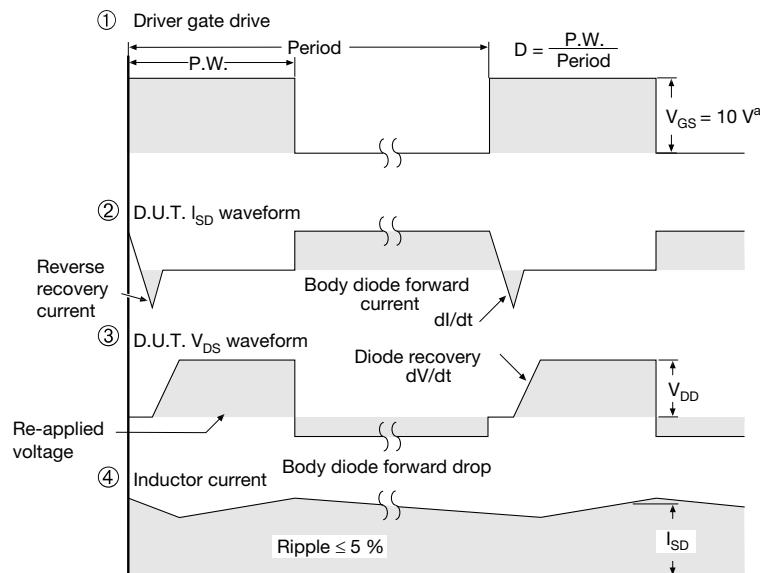
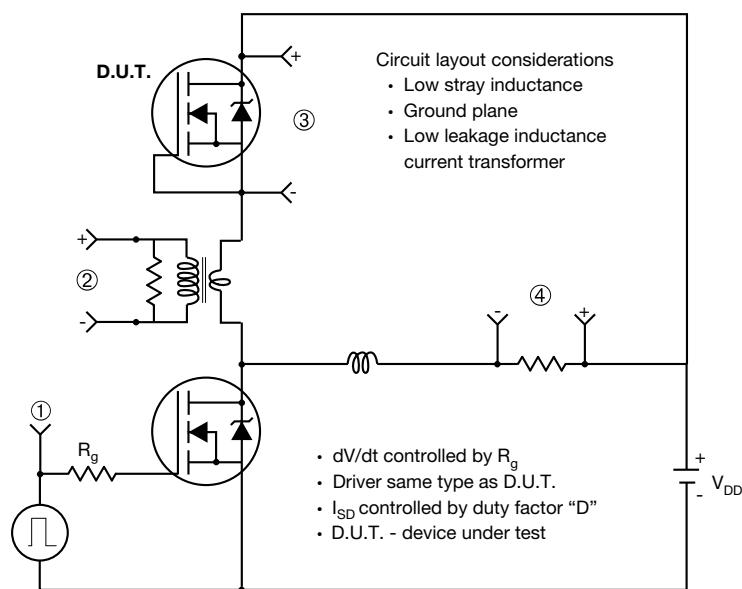
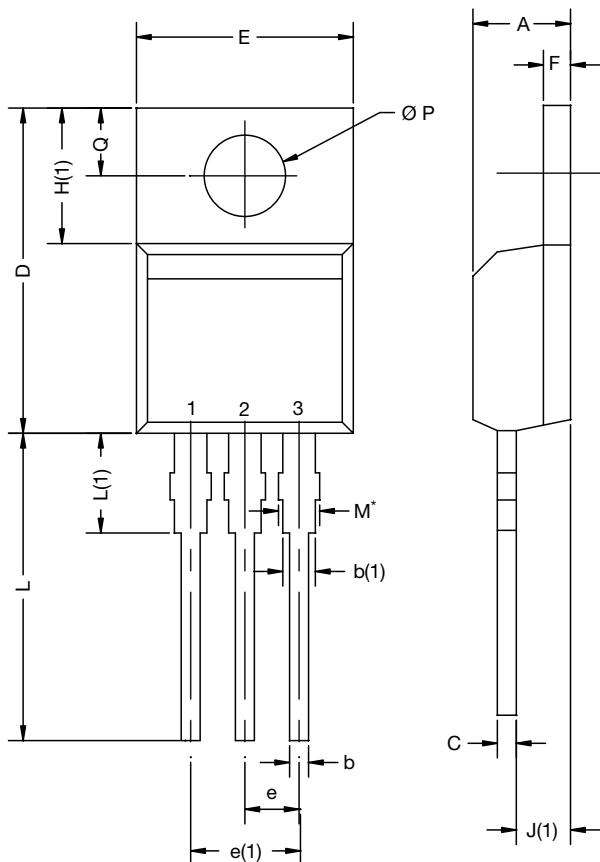


Fig. 18 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

Fig. 19 - For N-Channel

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TO-220-1



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
Ø P	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

ECN: X15-0364-Rev. C, 14-Dec-15
DWG: 6031

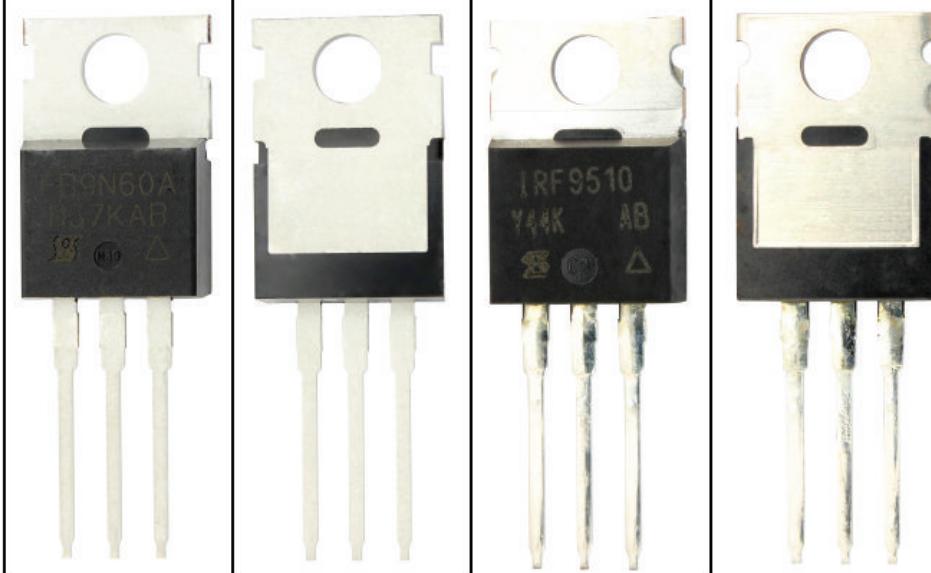
Note

- $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture

ASE

Xi'an



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